Booth No. **7A62-21**

CIT Co., Ltd.

Year Established	2023	Type of Business	Manufacturing
Website	https://globalcit.co.kr/	Main Export Countries	Germany
Domestic Customers	LAPP Cable, HL MANDO, MIT	International Customers	

The Person In Charge

Name	JI SUNG YU	Position	Sales Team Leader
Phone	+82-51-517-0302	E-mail	cred2@globalcit.co.kr

Company Description

CIT is an IT Material Company for Ultra-Fast Data Transmission.

Product

CuFlat-PKGCore™

Function and Usage

CIT's CuFlat-PKGCore™ is a glass core packaging substrate for next-generation AI accelerators. By depositing an ultra-flat copper layer onto a glass substrate, it enables high-speed, large-capacity data processing with superior electrical resistance and heat dissipation compared to conventional substrates.

Marketing and Selling points

CIT offers CuFlat-PKGCore™, an advanced packaging substrate featuring ultra-flat copper (roughness < 4 nm) and excellent thermal stability, achieved through a proprietary dry copper deposition process.
It also enables process simplification and reduces carbon emissions by 95%.